

MICROMEGAS Read-Out Chip

Réunion technique

LAPP, France

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FRANCE

April 7th, 2011

Outline

Introduction

Tests at LAPP

Tests at LAL

Production tests

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Tests at LAPP

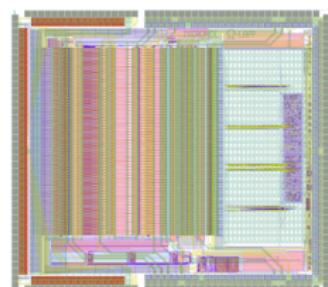
Tests at LAL

Production tests

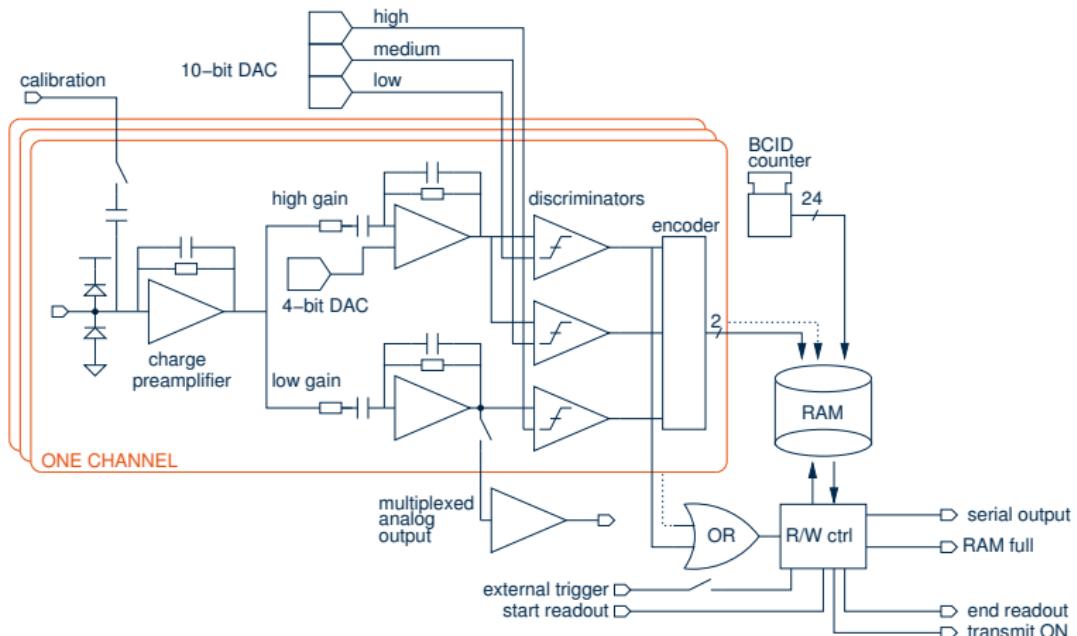
Introduction

MICROROC is a 64 channels integrated circuit packaged in TQFP160 intended to be used with MPGD-based DHCAL (MICROMEGAS or GEM).

- MICROROC is a fruit of the collaboration between LAPP and LAL/OMEGA based on the experience of previous ASICs (DIRAC and HARDROC) and on multiple test beam results
- Same Digital part as HARDROC2b, but charge preamplifier input stage + sparks protection [R. Gaglione] and slower shaping + 4-bit DAC offset correction per channel [N. Seguin]
- MICROROC is pin a pin compatible with the HARDROC2b to minimize boards modifications (see Cyril's talk).



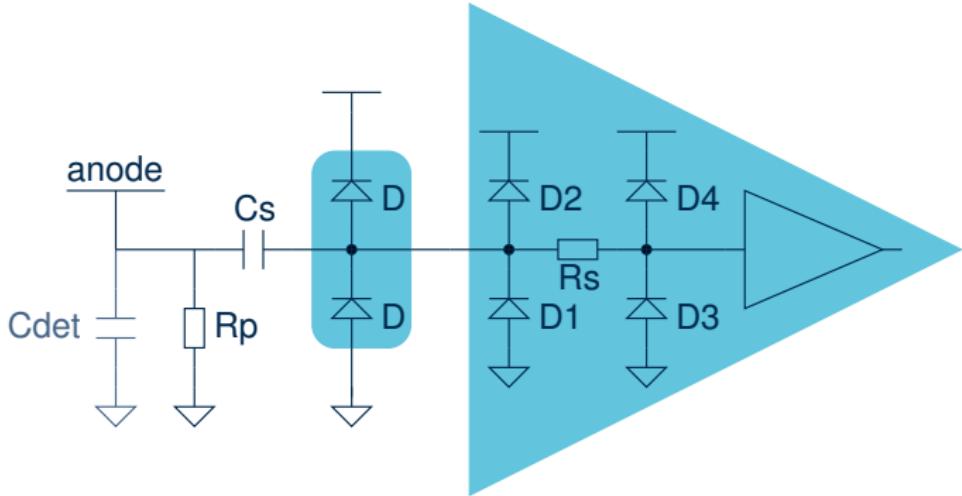
Global architecture



Performances

- Technology: AustriaMicroSystem SiGe 0.35 μ m
- Die size: 4.85×4.3 mm
- Dynamic range: 500 fC
- C_{det} : 80 pF
- Preamplifier gain: 2.38 mV/fC
- Noise rms: 1 fC at preamplifier output, 0.24 fC with 200 ns shaping
- Peaking times: 30, 50, 100 and 200 ns
- Minimum threshold: \sim 2 fC

Protection against sparks



$R_p=1 \text{ M}\Omega$, $R_s=10 \Omega$, $C_s=470 \text{ pF}$, D are ON-Semiconductor NUP 4114, D_x are integrated fast diodes.

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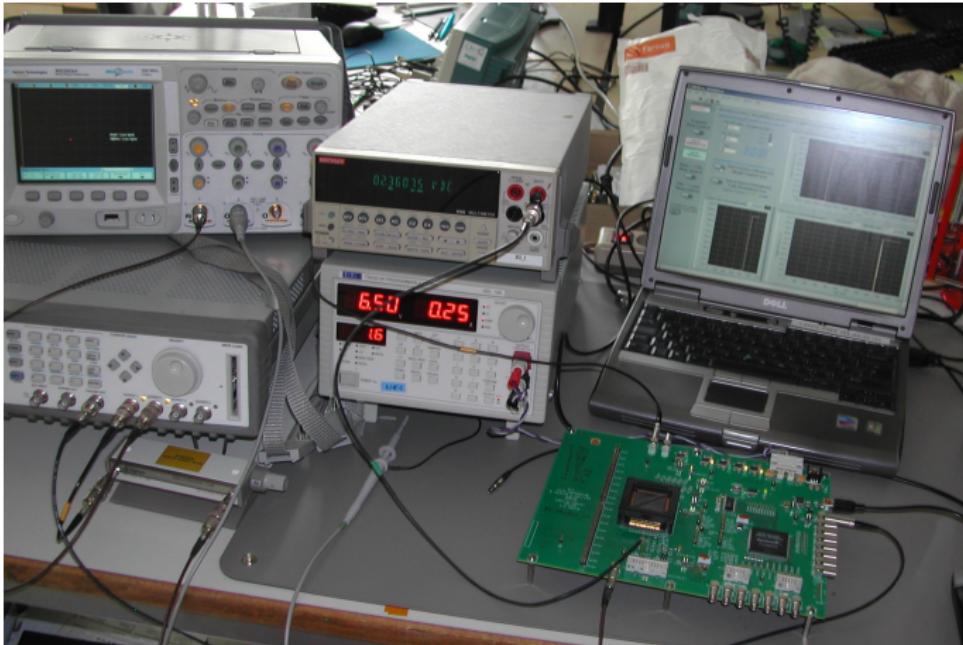
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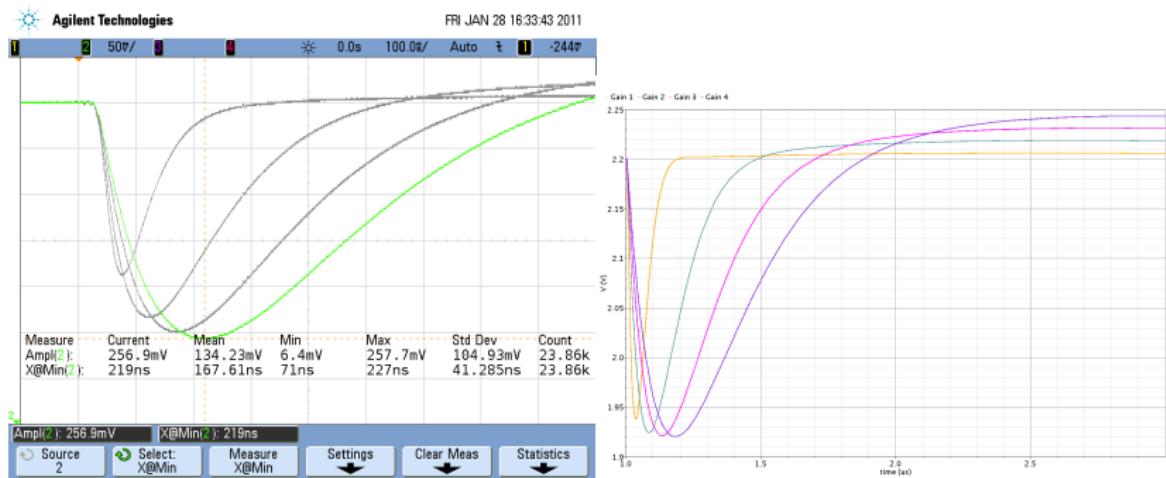
Test bench

The test board and labview software have been provided by OMEGA/LAL.



Waveforms

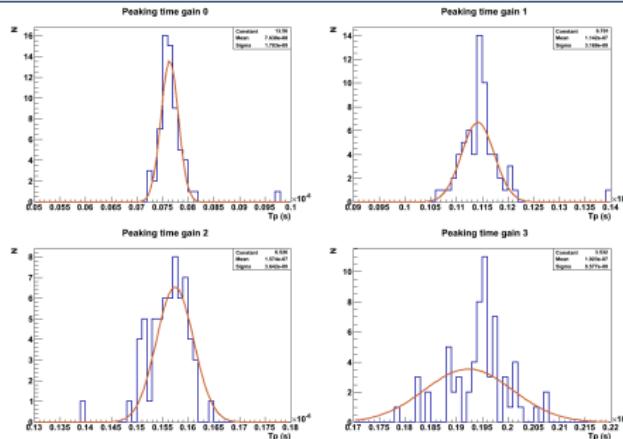
This is the output of high gain shaper, for the for settings (measure against simulation), with 25 fC charge injection (MIP-MPPV):



Good agreement between simulation and real behaviour.

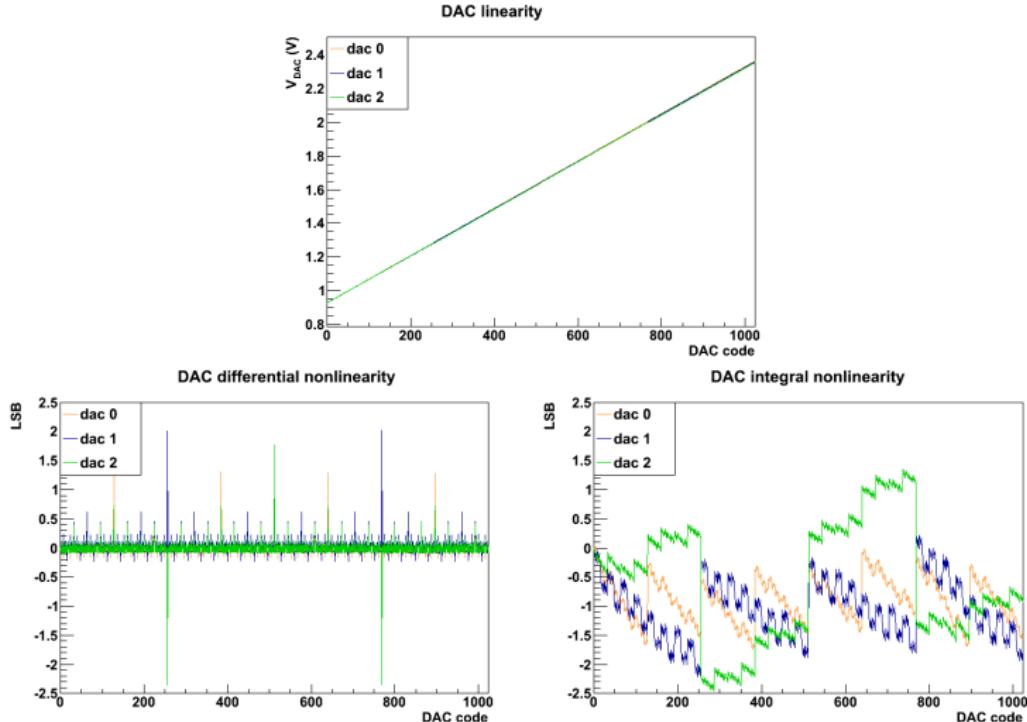
Shapers

Setting	Measure		Simulation	
	Gain (mV/fC)	T _p (ns)	Gain (mV/fC)	T _p (ns)
00	7.6	76.3	10.5	30
01	9.7	114.2	11.0	100
10	9.8	157.4	11.1	150
11	10.2	192.3	11.2	200



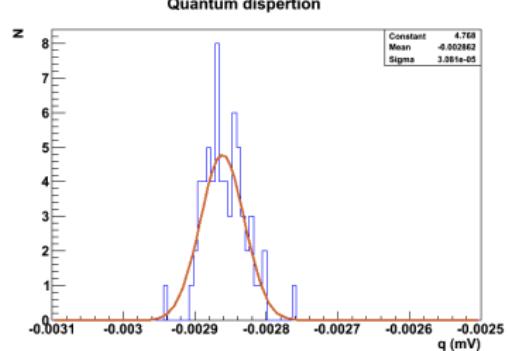
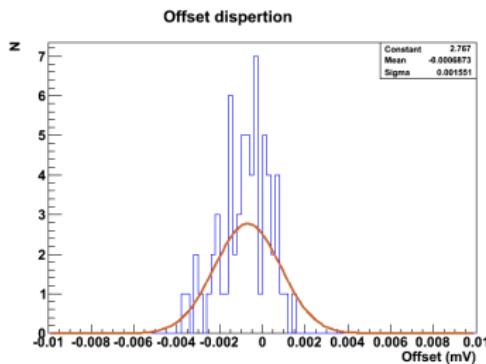
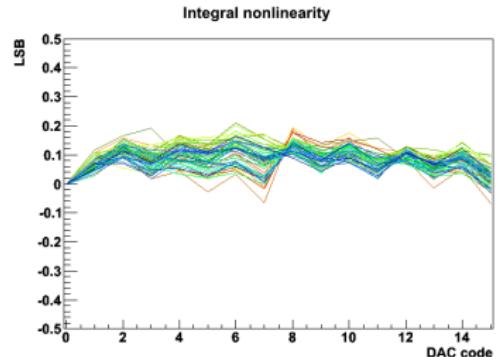
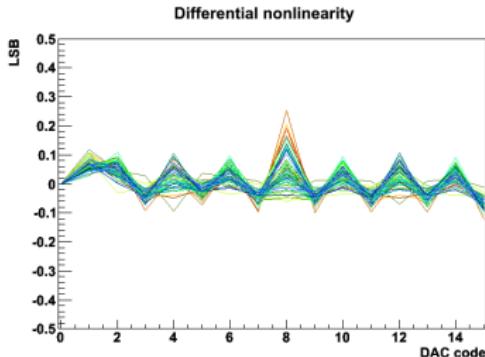
Good agreement between simulation and real behaviour.

Thresholds DAC



For each DAC, the linearity is about 3 DACU.

Offset correction DAC



The linearity is better than 1 DACU and $q=2.8$ mV.

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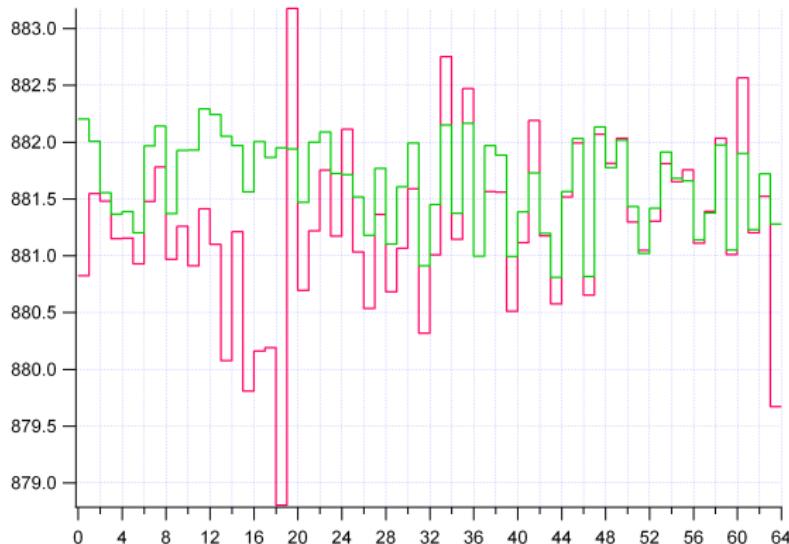
Pedestals compensation

$V_{avg} = 881.2$ DACU

$V_{sdev} = 0.74$ DACU

$V_{avg} = 881.6$ DACU

$V_{sdev} = 0.4$ DACU



Difference before and after correction, for high gain shaper: **2 factor on pedestal dispersion !**

Threshold DAC tests

dac0 slope:

1.37 mV/DACU

942.06 mV to 2.34 V

dac1 slope:

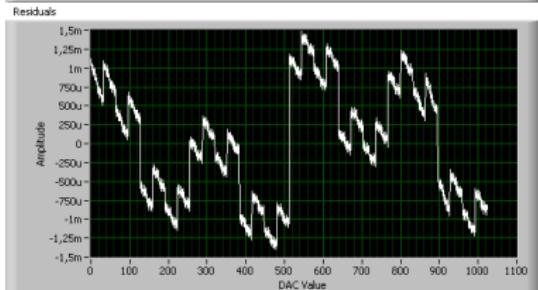
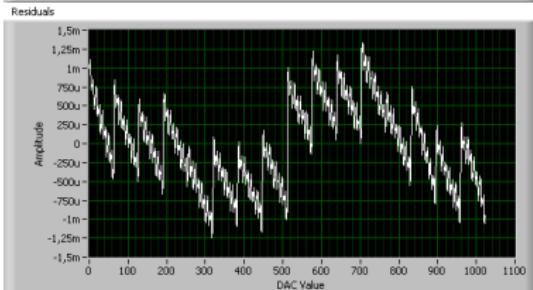
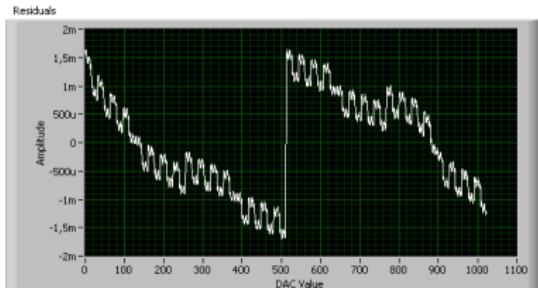
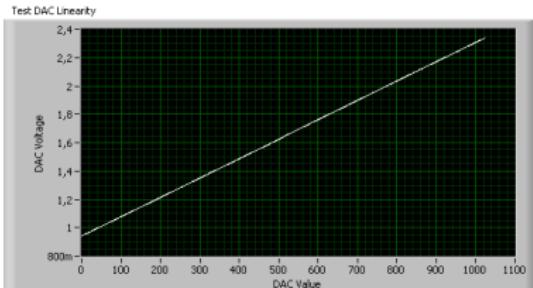
1.38 mV/DACU

943.32 mV to 2.35 V

dac2 slope:

1.37 mV/DACU

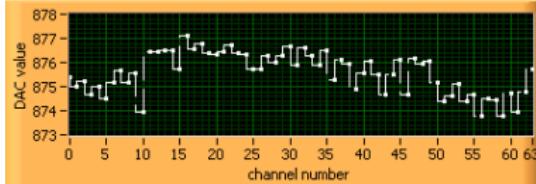
943.35 mV to 2.34 V



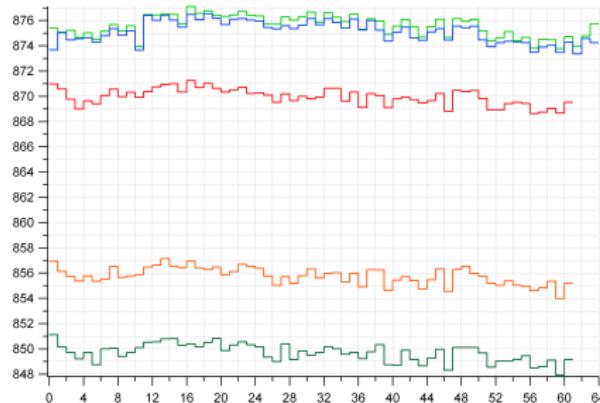
INL: ± 1.5 mV

Scurves measurements $C_{det}=88 \text{ pF}$

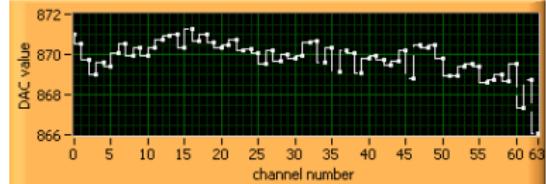
50%estimation per channel



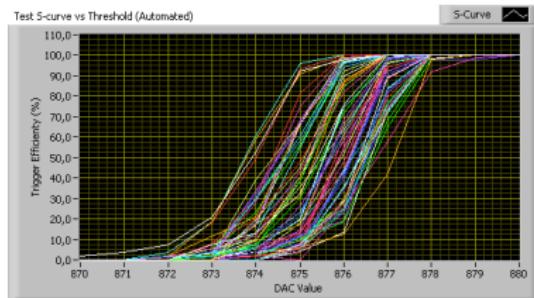
Pedestal: $V_{avg}= 875.6$; $V_{sdev}= 0.85$



50%estimation per channel



2 fC: $V_{avg}= 869.9$; $V_{sdev}= 0.65$



pedestal, 1 fC, 2 fC, 4 fC, 5 fC

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Status

Prototypes tests

The chip has been sent in MPW run in June 2010 and 5 prototypes have been received in September 2011. The behaviour of the prototypes is very satisfying.

Production

After prototypes tests in LAL and LAPP, an order has been placed for 350 chips. 341 chips have been received last week, and tests should be started very soon !

A production HR2b board has been flashed with Guillaume's DIF firmware and is used with Cyril's Labview to test the 341 chips.

Tests results

144 chips have been hand-tested and selected to equip the first square meter. For the second square meter, possibilty to use Mind's robot...
To be discussed !

Test procedure

Maximum gain, offset correction at 7 for all channels.

- Test all inputs bonding (exept channel 8: bad connection on socket) ;
- S-Curves without injection (pedestal) ;
- S-Curves with 25 fC.

Gain for each channel is extracted with framework. If any channel has a bad bonding or a wrong gain, chip is rejected.

Issues

Very poor yield (168/195:86%), but:

- Bonding tests seems not repeatable (socket?) ;
- Some corrupted data ;
- When Labview is launched, data of fist chip are not correct (bad dif id) ;
- Socket bound some pins: manually repaired !

All suspicious chip will be retested, and we hope a better yield !